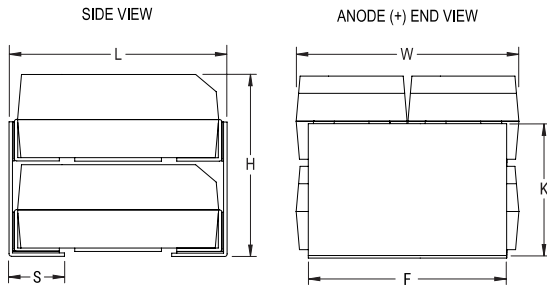


TSP, Tantalum, Polymer Tantalum, HRA, 130 uF, 20%, 50 VDC, 4X



Dimensions	
Case Code	4X
L	8mm +/-0.38mm
W	8.9mm +/-0.2mm
H	8.9mm +/-0.38mm
S	1.9mm +/-0.38mm
F	7.4mm +/-0.2mm
K	6.9mm +/-0.38mm

Packaging Specifications	
Packaging:	Tray
Packaging Quantity:	50

General Information	
Series:	TSP
Dielectric:	Polymer Tantalum
Style:	Stacked Chip
Description:	SMD, Polymer, KO, Stacks, High Reliability
Features:	High Reliability
RoHS:	No
Prop 65:	WARNING: Cancer and reproductive harm - www.p65warnings.ca.gov
SCIP Number:	30e82d35-b509-48ec-8c77-2d5ec01b3abc
Termination:	Solder Coated
Termination (Stack):	Solder Coated
AEC-Q200:	No
MSL:	3

Specifications	
Capacitance:	130 uF
Capacitance Tolerance:	20%
Voltage DC:	50 VDC (105C), 33.5 VDC (125C)
Temperature Range:	-55/+125°C
Rated Temperature:	105°C
Dissipation Factor:	10% 120Hz 25C
Failure Rate:	N/A
Resistance:	20 mOhms (100kHz 25C)
Leakage Current:	650 uA (5min 25°C)
Testing and Reliability:	10 Cycles Surge Current Testing At -55C +0C/-5C And +85C +/-5C After Voltage Aging

单击下面可查看定价，库存，交付和生命周期等信息

[>>KEMET\(基美\)](#)